

**Please amend the Claims as follows:**

1-3. (Cancelled)

4. (Currently Amended) A thin-film capacitor element comprising:  
an insulative substrate having a via hole filled with a conductive  
material;  
a lower electrode;  
a dielectric layer; and  
an upper electrode;  
wherein the lower electrode, the dielectric layer on the lower  
electrode, and the upper electrode on the dielectric layer are disposed  
successively deposited in order on the insulative substrate, at least a portion  
of the upper and lower electrodes overlap with the dielectric layer  
therebetween in a direction perpendicular to a face of the substrate,  
either one of the lower electrode and the upper electrode  
connects to an end face of the conductive material in an area not having a  
dielectric layer; and  
the dielectric layer is shaped like a ring to surround the via hole.

5. (Previously Presented) A thin-film capacitor element according to  
Claim 4, wherein an area between the dielectric layer and the via hole is ring  
shaped.

6. (Previously Presented) A thin-film capacitor element according to  
Claim 4, wherein the insulative substrate is made of low-temperature-sintered  
ceramic.

7. (New) A thin-film capacitor element according to Claim 4,  
wherein the lower electrode connects to the end face of the conductive  
material.

8. (New) A thin-film capacitor element according to Claim 7,  
wherein a substantial portion of the circumference of the lower electrode is not

covered by the dielectric layer and a substantial portion of the circumference of the dielectric layer is not covered by the upper electrode.

9. (New) A thin-film capacitor element according to Claim 4, wherein the upper electrode connects to the end face of the conductive material.

10. (New) A thin-film capacitor element according to Claim 9, wherein the entire circumference of the lower electrode is not covered by the dielectric layer and the entire circumference of the dielectric layer is not covered by the upper electrode.

11. (New) A thin-film capacitor element according to Claim 9, wherein the lower electrode and a portion of the upper electrode surrounding the area that connects to the end face of the conductive material contact the insulative substrate.

12. (New) A thin-film capacitor element according to Claim 11, wherein the dielectric layer is disposed on the insulative substrate between the lower electrode and the portion of the upper electrode that contacts the insulative substrate.